External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped Silicon	Silicon (Si)	7440-21-3	0.47576	100.0	25.56
			Subtotal	0.47576	100	25.56
Lead Frame		Phosphorous (P)	7723-14-0	0.0188	0.03	1.00983
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.67668	1.08	36.35388
		Copper (Cu)	7440-50-8	61.95984	98.89	3,328.73629
			Subtotal	62.65532	100	NaN
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.65911	7.7	142.8581
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.14406	12.0	222.636
	Filler	Silica fused	60676-86-0	27.62708	80.0	1,484.24
	Carbon Black	Carbon black	1333-86-4	0.1036	0.3	5.5659
			Subtotal	34.53385	100	NaN
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.78132	100.0	95.7
			Subtotal	1.78132	100	95.7
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.26002	100.0	13.96932
			Subtotal	0.26002	100	13.96932
Solder Wire	Pure metal	Tin (Sn)	7440-31-5	0.01469	5.0	0.789
	Pure metal	Silver (Ag)	7440-22-4	0.00441	1.5	0.2367
	Pure metal	Lead (Pb)	7439-92-1	0.27463	93.5	14.7543
			Subtotal	0.29373	100	15.78
			Total	100	100	NaN